PROCESS FOR EXPOSING SOLDER BUMPS ON AN UNDERFILL COATED SEMICONDUCTOR

ABSTRACT OF THE INVENTION

A process for applying a solvent-free underfill onto a bumped semiconductor comprises: providing an underfill in a compressible state on a semiconductor, contacting the underfill with a compliant surface and applying sufficient pressure to expose the bumps, optionally hardening the underfill to a solid state, and removing the compliant surface.

Figure 3